



## General Description

The Si2328DS-T1-GE3 use advanced SGT MOSFET technology to provide low RDS(ON), low gate charge, fast switching and excellent avalanche characteristics.

This device is specially designed to get better ruggedness and suitable to use in



## General Features

$V_{DS} = 100V$   $I_D = 5 A$

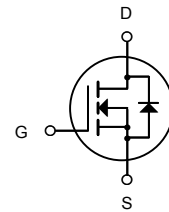
$R_{DS(ON)} < 140m\Omega @ V_{GS} = 10V$

## Applications

Consumer electronic power supply Motor control

Synchronous-rectification Isolated DC

Synchronous-rectification applications



N-Channel MOSFET

## Ordering Information

Product ID	Pack	Brand	Qty(PCS)
Si2328DS-T1-GE3	SOT-23-3L	HXY MOSFET	3000

## Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	5	A
$I_D @ T_c = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	2.2	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	11	A
$P_D @ T_c = 25^\circ C$	Total Power Dissipation <sup>4</sup>	1	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JC}$	Thermal Resistance from Junction-to-Ambient <sup>3</sup>	80	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	125	°C/W



### Electrical Characteristics $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	100	110	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 100V, V_{GS} = 0V$	-	-	1	$\mu A$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA
<b>On Characteristics</b> <sup>note3</sup>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.0	1.95	3.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance <sup>note2</sup>	$V_{GS} = 10V, I_D = 3A$	-	95	140	m $\Omega$
<b>Dynamic Characteristics</b> <sup>note4</sup>						
$C_{iss}$	Input Capacitance	$V_{DS} = 50V, V_{GS} = 0V,$ $f = 1.0MHz$	-	196	-	pF
$C_{oss}$	Output Capacitance		-	25.9	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	21.4	-	pF
$Q_g$	Total Gate Charge	$V_{DS} = 50V, I_D = 3A,$ $V_{GS} = 10V$	-	4.3	-	nC
$Q_{gs}$	Gate-Source Charge		-	3.5	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	3.1	-	nC
<b>Switching Characteristics</b> <sup>note4</sup>						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 50V, I_{DS}=3A$ $R_G = 2\Omega, V_{GEN} = 10V$	-	14.7	-	ns
$t_r$	Turn-On Rise Time		-	3.5	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	20.9	-	ns
$t_f$	Turn-Off Fall Time		-	2.7	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current <sup>note2</sup>		-	-	4.5	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	12	A
$V_{SD}$	Drain to Source Diode Forward Voltage <sup>note3</sup>	$V_{GS} = 0V, I_S = 3A$	-	-	1.3	V
$t_{rr}$	Body Diode Reverse Recovery Time	$V_{GS} = 0V, I_F = 3A,$ $di/dt = 100A/\mu s$	-	32.1	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Time Charge		-	39.4	-	nC
$I_{rrm}$	Peak Reverse Recovery Current		-	2.1	-	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5.  $V_{DD}=50$  V,  $R_G=50$   $\Omega$ ,  $L=0.3$  mH, starting  $T_j=25$   $^\circ\text{C}$



### Typical Characteristics

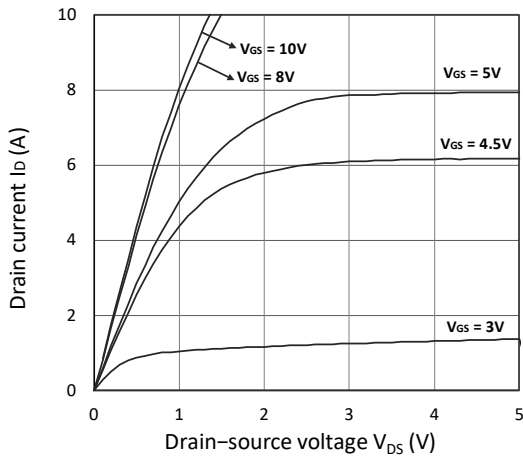


Figure 1. Output Characteristics

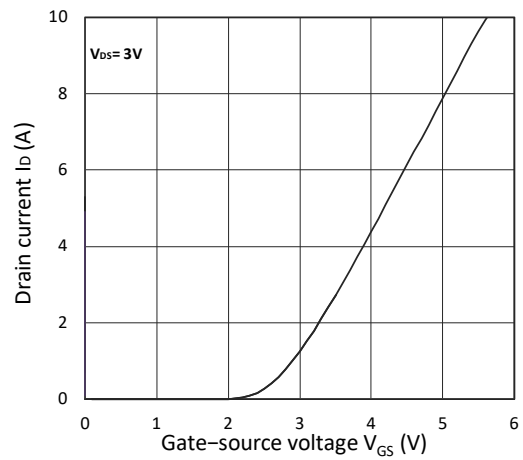


Figure 2. Transfer Characteristics

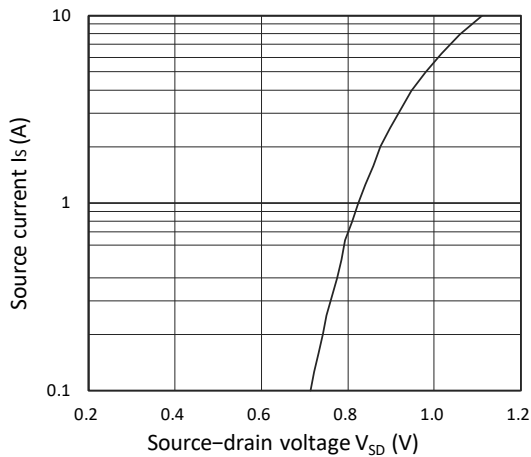


Figure 3. Forward Characteristics of Reverse

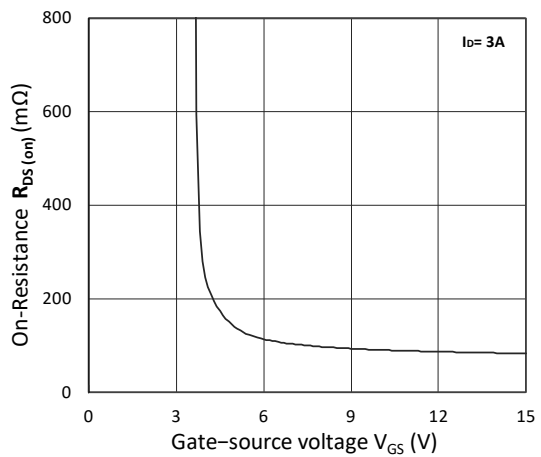


Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$

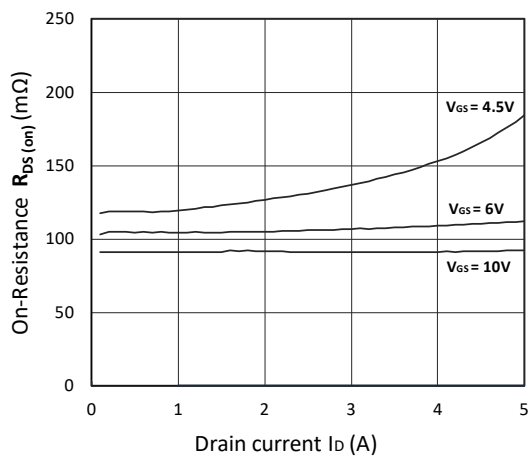


Figure 5.  $R_{DS(on)}$  vs.  $I_D$

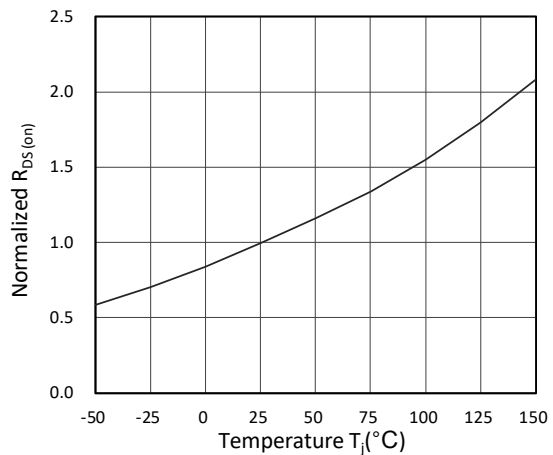


Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

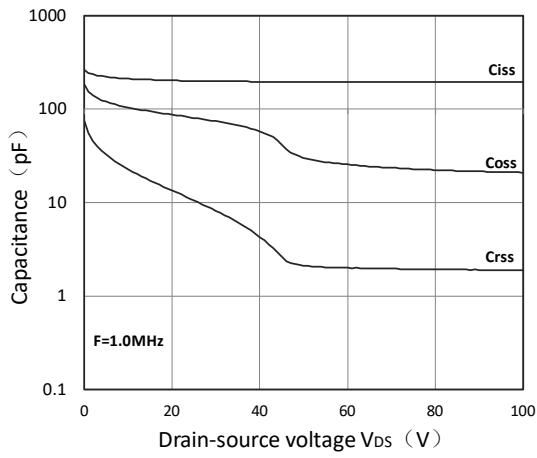


Figure 7. Capacitance Characteristics

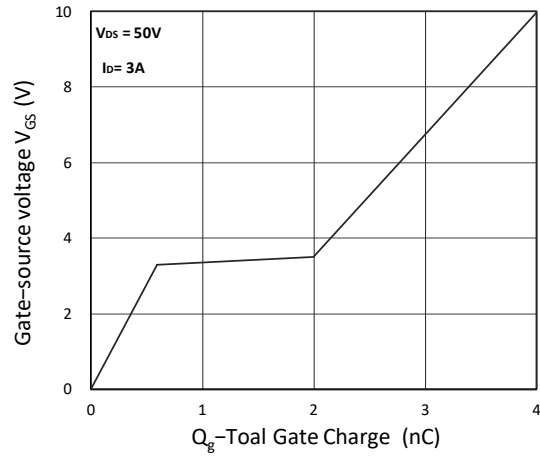
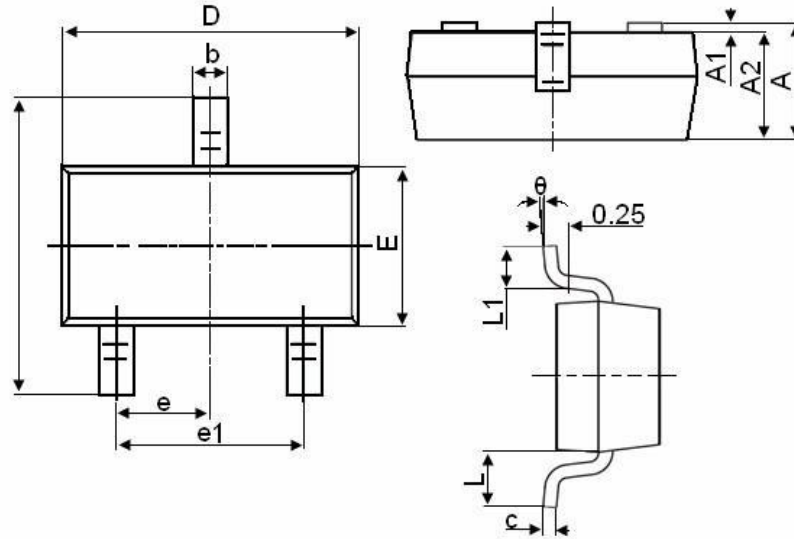


Figure 8. Gate Charge Characteristics



### SOT-23-3L Package Information



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.300	0.500
c	0.100	0.200
D	2.800	3.000
E	1.500	1.700
E1	2.650	2.950
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.600
θ	0°	8°



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